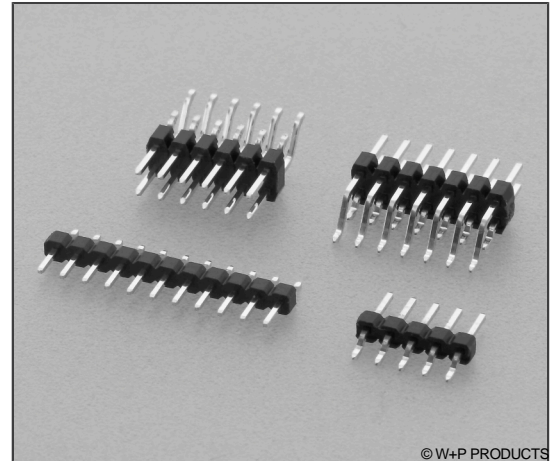


SMT-Stiftleisten RM 2,00mm, liegend, 1-/2-reihig SMT Pin Headers, 2.00mm Pitch, Horizontal, Single/Double Row

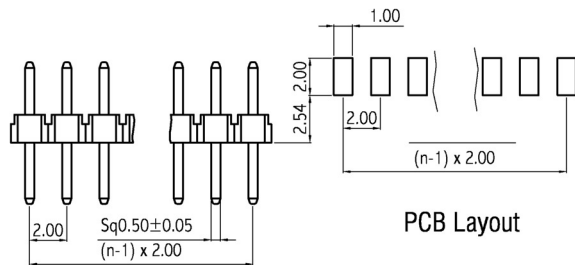
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Vierkantstift 0,50mm, Kupferlegierung <i>0.50mm square pin, copper alloy</i>
Kontaktfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni <i>Acc. to options (see below), over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 500 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC
Nennspannung <i>Voltage Rating</i>	250 V AC
Nennstrom <i>Current Rating</i>	1 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +125 °C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

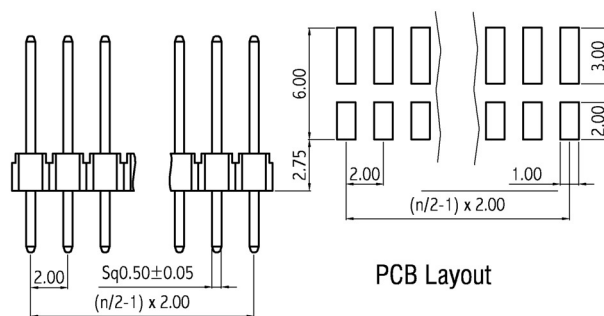


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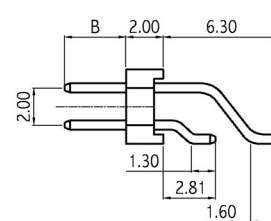
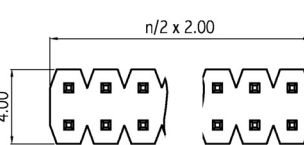
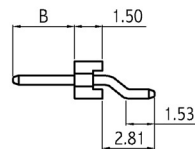
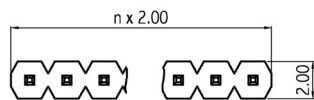
Passende Buchsenleisten:
Compatible Female Headers:
4160 7450 7451 etc.
Weitere siehe Kapitel B
Please see ch. B for more



PCB Layout



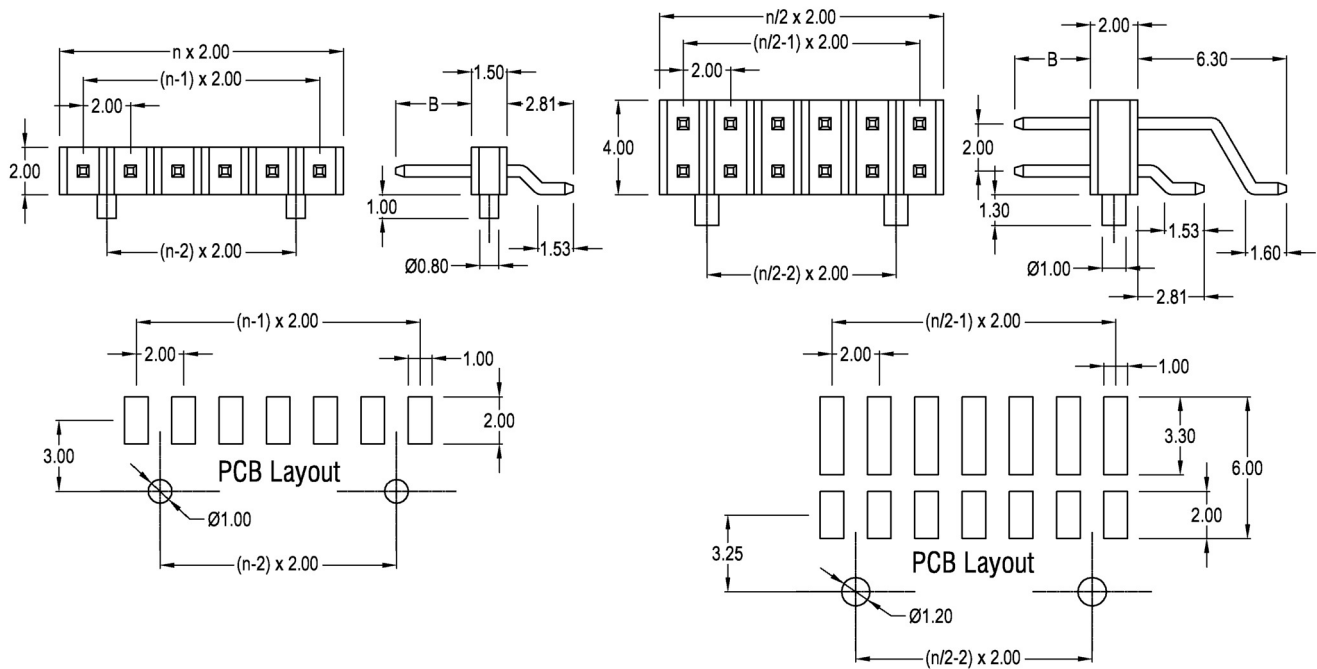
PCB Layout



Series	Contacts*	Rows*	Dimensions*	Plating*	Loc. Pegs	Packaging*
7353	36 02-36 Einreihig <i>Single row</i> 04-72 Zweireihig <i>Double row</i>	1 1 Einreihig <i>Single row</i> 2 Zweireihig <i>Double row</i>	10 10 B=3,20mm 11 B=4,45mm 99- Kundenspezifisch <i>Customer-specific</i>	50 00 Vergoldet <i>Gold plated</i> 50 Verzinkt <i>Tin plated</i> 60 Sel Au/Sn <i>Duplex plating</i>	00 00 Ohne Pos.hilfen <i>W/o locating pegs</i>	PPST ST PPST PPTR (Option)

7353

SMT-Stiftleisten RM 2,00mm, liegend, 1-/2-reihig
SMT Pin Headers, 2.00mm Pitch, Horizontal, Single/Double Row



Series	Contacts*	Rows*	Dimensions*	Plating*	Loc. Pegs	Packing*
7353	20 02-36 Einreihig Single row 04-72 Zweireihig Double row	2 1 Einreihig Single row 2 Zweireihig Double row	10 10 B=3,20mm 11 B=4,45mm 99- Kundenspezifisch Customer-specific	00 00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	10 10 Mit Pos.hilfen With locating pegs	ST ST PPST PPTR (Option)

* Dies ist ein **Bestellbeispiel** -
 bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** -
 please replace by your specifications.

Lieferformen / Packaging Options:
ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads
PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads
PPTR (Option) Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

